

## ISO-CMOS MT093 8 x 12 Analog Switch Array

**Data Sheet** 

#### Features

- Internal control latches and address decoder
- Short set-up and hold times
- Wide operating voltage: 4.5 V to 14.5 V
- 3.5Vpp analog signal capability
- R<sub>ON</sub> 65 Ω max. @ V<sub>DD</sub>=14V, 25°C
- $\Delta R_{ON} \le 10 \Omega$  @ V<sub>DD</sub>=14V, 25°C
- Full CMOS switch for low distortion
- Minimum feedthrough and crosstalk
- Low power consumption ISO-CMOS technology

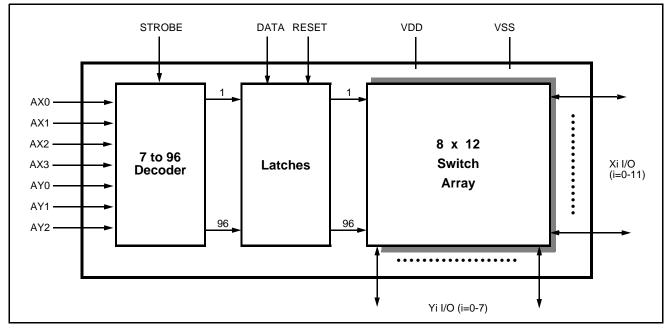
### Applications

- PBX systems
- Mobile radio
- Test equipment /instrumentation
- Analog/digital multiplexers
- Audio/Video switching

Ord	Ordering Information					
MT093AE1 MT093AP1 MT093APR1	40 Pin PDIP* 44 Pin PLCC* 44 Pin PLCC*	Tubes Tubes Tubes				
*P	b Free Matte Tin					
	0°C to +70°C					

### Description

The Zarlink MT093 is fabricated in Zarlink's ISO-CMOS technology providing low power dissipation and high reliability. The device contains a 8x12 array of crosspoint switches along with a 7 to 96 line decoder and latch circuits. Any one of the 96 switches can be addressed by selecting the appropriate seven input bits. The selected switch can be turned on or off by applying a logical one or zero to the DATA input.



#### Figure 1 - Functional Block Diagram

September 2011

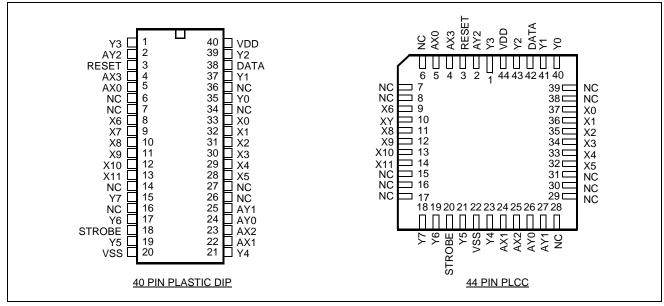


Figure 2 - Pin Connections

### Change Summary

Changes from the August 2005 issue to the September 2011 issue.

Page	ltem	Change
1	Ordering Information	Removed leaded packages as per PCN notice.

#### **Pin Description**

Pir	า #	Name	Description
PDIP	PLCC	Name	Description
1	1	Y3	<b>Y3 Analog (Input/Output):</b> this is connected to the Y3 column of the switch array.
2	2	AY2	Y2 Address Line (Input).
3	3	RESET	Master RESET (Input): this is used to turn off all switches. Active High.
4,5	4,5	AX3,AX0	X3 and X0 Address Lines (Inputs).
6,7	6-8	NC	No Connection.
8-13	9-14	X6-X11	<b>X6-X11 Analog (Inputs/Outputs):</b> these are connected to the X6-X11 rows of the switch array.
14	15-17	NC	No Connection.
15	18	Y7	<b>Y7 Analog (Input/Output):</b> this is connected to the Y7 column of the switch array.
16	-	NC	No Connection.
17	19	Y6	Y6 Analog (Input/Output): this is connected to the Y6 column of the switch array.

#### **Pin Description**

Pir	n #	Name	Description
PDIP	PLCC	Name	Description
18	20	STROBE	<b>STROBE (Input)</b> : enables function selected by address and data. Address must be stable before STROBE goes high and DATA must be stable on the falling edge of the STROBE. Active High.
19	21	Y5	<b>Y5 Analog (Input/Output):</b> this is connected to the Y5 column of the switch array.
20	22	V <sub>SS</sub>	Ground Reference.
21	23	Y4	<b>Y4 Analog (Input/Output):</b> this is connected to the Y4 column of the switch array.
22, 23	24,25	AX1,AX2	X1 and X2 Address Lines (Inputs).
24, 25	26,27	AY0,AY1	Y0 and Y1 Address Lines (Inputs).
26, 27	28-31	NC	No Connection.
28 - 33	32-37	X5-X0	<b>X5-X0 Analog (Inputs/Outputs):</b> these are connected to the X5-X0 rows of the switch array.
34	38,39	NC	No Connection.
35	40	Y0	Y0 Analog (Input/Output): this is connected to the Y0 column of the switch array.
36	-	NC	No Connection.
37	41	Y1	Y1 Analog (Input/Output): this is connected to the Y1 column of the switch array.
38	42	DATA	<b>DATA (Input)</b> : a logic high input will turn on the selected switch and a logic low will turn off the selected switch. Active High.
39	43	Y2	Y2 Analog (Input/Output): this is connected to the Y2 column of the switch array.
40	44	V <sub>DD</sub>	Positive Power Supply.

#### **Functional Description**

The MT093 is an analog switch matrix with an array size of 8 x 12. The switch array is arranged such that there are 8 columns by 12 rows. The columns are referred to as the Y input/output lines and the rows are the X input/output lines. The crosspoint analog switch array will interconnect any X line with any Y line when turned on and provide a high degree of isolation when turned off. The control memory consists of a 96 bit write only RAM in which the bits are selected by the address input lines (AY0-AY2, AX0-AX3). Data is presented to the memory on the DATA input line. Data is asynchronously written into memory whenever the STROBE input is high and is latched on the falling edge of STROBE. A logical "1" written into a memory cell turns the corresponding crosspoint switch on and a logical "0" turns the crosspoint off. Only the crosspoint switches corresponding to the addressed memory location are altered when data is written into memory. The remaining switches retain their previous states. Any combination of X and Y lines can be interconnected by establishing appropriate patterns in the control memory. A logical "1" on the RESET input line will asynchronously return all memory locations to logical "0" turning off all crosspoint switches.

#### Address Decode

The seven address lines along with the STROBE input are logically ANDed to form an enable signal for the resettable transparent latches. The DATA input is buffered and is used as the input to all latches. To write to a location, RESET must be low while the address and data lines are set up. Then the STROBE input is set high and then low causing the data to be latched. The data can be changed while STROBE is high, however, the corresponding switch will turn on and off in accordance with the data. Data must be stable on the falling edge of STROBE in order for correct data to be written to the latch.

	Parameter	Symbol	Min.	Max.	Units
1	Supply Voltage	V <sub>DD</sub> V <sub>SS</sub>	-0.3 -0.3	16.0 V <sub>DD</sub> +0.3	V V
2	Analog Input Voltage	V <sub>INA</sub>	-0.3	V <sub>DD</sub> +0.3	V
3	Digital Input Voltage	V <sub>IN</sub>	V <sub>SS</sub> -0.3	V <sub>DD</sub> +0.3	V
4	Current on any I/O Pin	I		±15	mA
5	Storage Temperature	Τ <sub>S</sub>	-65	+150	°C
6	Package Power Dissipation PLASTIC DIP	P <sub>D</sub>		0.6	W

Absolute Maximum Ratings\*- Voltages are with respect to V<sub>SS</sub> unless otherwise stated.

\* Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied.

#### Recommended Operating Conditions - Voltages are with respect to V<sub>SS</sub> unless otherwise stated.

	Characteristics	Sym.	Min.	Тур.	Max.	Units	Test Conditions
1	Operating Temperature	Т <sub>О</sub>	0	25	70	°C	
2	Supply Voltage	V <sub>DD</sub>	4.5		14.5	V	
3	Analog Input Voltage	V <sub>INA</sub>	$V_{SS}$		3.5	V	
4	Digital Input Voltage	V <sub>IN</sub>	$V_{SS}$		$V_{DD}$	V	

## **DC Electrical Characteristics**<sup>†</sup>- Voltages are with respect to $V_{SS}$ =0V, $V_{DD}$ =14V unless otherwise stated.

	Characteristics	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	Quiescent Supply Current	I <sub>DDQ</sub>		1	100	μΑ	All digital inputs at $V_{\text{IN}}\text{=}V_{\text{SS}}$ or $V_{\text{DD}}$
				7	15	mA	All digital inputs at V <sub>IN</sub> =2.4V
2	Off-state Leakage Current	I <sub>OFF</sub>			±1	μA	$IV_{Xi} - V_{Yj}I = V_{DD} - V_{SS}$
3	Input Logic "0" level	V <sub>IL</sub>			0.8	V	
4	Input Logic "1" level	V <sub>IH</sub>	2.4			V	
5	Input Leakage (digital pins)	I <sub>LEAK</sub>			10	μΑ	All digital inputs at $V_{IN} = V_{SS}$ or $V_{DD}$

† DC Electrical Characteristics are over recommended temperature range & recommended power supply voltages.

‡ Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

	Characteristics	Sym.	25	S°C	60	0°C	70°C		Units	Test Conditions
			Тур.	Max.	Тур.	Max.	Тур.	Max.		
1	On-state V <sub>DD</sub> =14V Resistance	R <sub>ON</sub>	45	65				75	Ω	V <sub>SS</sub> =0V, IV <sub>Xi</sub> -V <sub>YI</sub> I = 0.25V V <sub>IDC</sub> =6.75V V <sub>ODC</sub> =6.5V
2	Difference in on-state resistance between two switches	∆R <sub>ON</sub>	5	10		10		10		$V_{DD}=14V, V_{SS}=0, \\ V_{IDC}=6.75V \\ V_{ODC}=6.5V \\ IV_{Xi}-V_{Yj}I = 0.25V \\ \label{eq:VDC}$

#### DC Electrical Characteristics- Switch Resistance - VIDC/VODC is the external DC offset applied at the analog I/O pins.

## AC Electrical Characteristics<sup>†</sup> - Crosspoint Performance- $V_{DC}$ is the external DC offset applied at the analog I/O pins. Voltages are with respect to $V_{DD}$ =7V, $V_{DC}$ =0V, $V_{SS}$ =-7V, unless otherwise stated.

	Characteristics	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	Switch I/O Capacitance	CS		20		pF	f=1 MHz
2	Feedthrough Capacitance	C <sub>F</sub>		0.2		pF	f=1 MHz
3	Frequency Response Channel "ON" 20LOG(V <sub>OUT</sub> /V <sub>Xi</sub> )=-3dB	F <sub>3dB</sub>		45		MHz	Switch is "ON"; $V_{INA} = 2Vpp$ sinewave; $R_L = 1k\Omega$
4	Total Harmonic Distortion	THD		0.05		%	Switch is "ON"; $V_{INA} = 2Vpp$ sinewave f= 1kHz; $R_L=1k\Omega$
5	Feedthrough Channel "OFF" Feed.=20LOG (V <sub>OUT</sub> /V <sub>Xi</sub> )	FDT		-95		dB	All Switches "OFF"; $V_{INA}$ = 2Vpp sinewave f= 1kHz; $R_L$ = 1k $\Omega$ .
6	Crosstalk between any two channels for switches Xi-Yi and	X <sub>talk</sub>		-45		dB	$V_{INA}$ =2Vpp sinewave f= 10MHz; R <sub>L</sub> = 75Ω.
	Xj-Yj. Xtalk=20LOG (V <sub>Yi</sub> /V <sub>Xi</sub> ).			-90		dB	$V_{INA}$ =2Vpp sinewave f= 10kHz; R <sub>L</sub> = 600 $\Omega$ .
				-85		dB	V <sub>INA</sub> =2Vpp sinewave f= 10kHz; R <sub>L</sub> = 1kΩ.
				-80		dB	$V_{INA}$ =2Vpp sinewave f= 1kHz; R <sub>L</sub> = 10k $\Omega$ .
7	Propagation delay through switch	t <sub>PS</sub>			50	ns	$R_L=1k\Omega; C_L=50pF$

† Timing is over recommended temperature range.

‡ Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing. Crosstalk measurements are for Plastic DIPS only, crosstalk values for PLCC packages are approximately 5 dB better.

	Characteristics	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	Control Input crosstalk to switch (for DATA, STROBE, Address)	CX <sub>talk</sub>		50		mVpp	$V_{IN}$ =3V+V <sub>DC</sub> squarewave; R <sub>IN</sub> =1k $\Omega$ , R <sub>L</sub> =10k $\Omega$ .
2	Digital Input Capacitance	C <sub>DI</sub>		10		pF	f=1MHz
3	Switching Frequency	Fo			10	MHz	
4	Setup Time DATA to STROBE	t <sub>DS</sub>	20			ns	$R_L = 1k\Omega$ , $C_L = 50pF$
5	Hold Time DATA to STROBE	t <sub>DH</sub>	20			ns	$R_L = 1k\Omega$ , $C_L = 50pF$
6	Setup Time Address to STROBE	t <sub>AS</sub>	20			ns	$R_L = 1k\Omega$ , $C_L = 50pF$
7	Hold Time Address to STROBE	t <sub>AH</sub>	20			ns	$R_L = 1k\Omega$ , $C_L = 50pF$
8	STROBE Pulse Width	t <sub>SPW</sub>	40			ns	$R_L = 1k\Omega$ , $C_L = 50pF$
9	RESET Pulse Width	t <sub>RPW</sub>	80			ns	$R_L = 1k\Omega$ , $C_L = 50pF$
10	STROBE to Switch Status Delay	t <sub>S</sub>		80	200	ns	$R_L = 1k\Omega$ , $C_L = 50pF$
11	DATA to Switch Status Delay	t <sub>D</sub>		100	200	ns	$R_L = 1k\Omega$ , $C_L = 50pF$
12	RESET to Switch Status Delay	t <sub>R</sub>		70	200	ns	$R_L = 1k\Omega$ , $C_L = 50pF$

## **AC Electrical Characteristics<sup>†</sup> - Control and I/O Timings**- V<sub>DC</sub> is the external DC offset applied at the analog I/O pins. Voltages are with respect to V<sub>DD</sub>=7V, V<sub>DC</sub>=0V, V<sub>SS</sub>=-7V, unless otherwise stated.

† Timing is over recommended temperature range.
 Digital Input rise time (tr) and fall time (tf) = 10 ns.
 ‡ Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

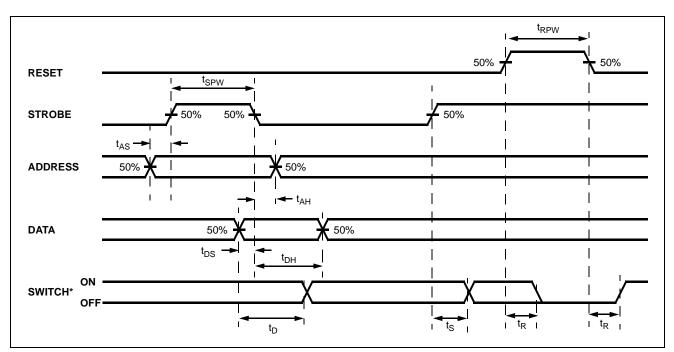


Figure 3 - Control Memory Timing Diagram

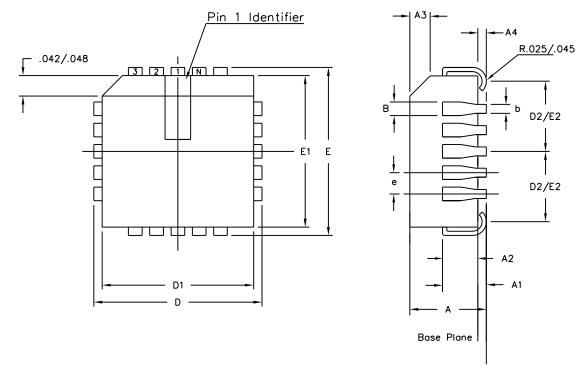
[	AX0	AX1	AX2	AX3	AY0	AY1	AY2	Connection
00	0	0	0	0	0	0	0	X0-Y0
10	1	0	0	0	0	0	0	X1-Y0
20	0	1	0	0	0	0	0	X2-Y0
30	1	1	0	0	0	0	0	X3-Y0
40	0	0	1	0	0	0	0	X4-Y0
50	1	0	1	0	0	0	0	X5-Y0
	0	1	1	0	0	0	0	No Connection
	1	1	1	0	0	0	0	No Connection
80	0	0	0	1	0	0	0	X6-Y0
90	1	0	0	1	0	0	0	X7-Y0
A0	0	1	0	1	0	0	0	X8-Y0
B0	1	1	0	1	0	0	0	X9-Y0
C0	0	0	1	1	0	0	0	X10-Y0
D0	1	0	1	1	0	0	0	X11-Y0
	0	1	1	1	0	0	0	No Connection
	1	1	1	1	0	0	0	No Connection
	0	0	0	0	1	0	0	X0-Y1
	$\downarrow$	$\downarrow \downarrow$						
	1	0	1	1	1	0	0	X11-Y1
	0	0	0	0	0	1	0	X0-Y2
	$\downarrow$	$\downarrow \downarrow$						
	1	0	1	1	0	1	0	X11-Y2
	0	0	0	0	1	1	0	X0-Y3
	$\downarrow$	$\downarrow \downarrow$						
	1	0	1	1	1	1	0	X11-Y3
	0	0	0	0	0	0	1	X0-Y4
	$\downarrow$	$\downarrow \downarrow$						
	1	0	1	1	0	0	1	X11-Y4
	0	0	0	0	1	0	1	X0-Y5
	$\downarrow$	$\downarrow \downarrow$						
	1	0	1	1	1	0	1	X11-Y5
	0	0	0	0	0	1	1	X0-Y6
	Ļ	$\downarrow$	$\downarrow$	Ļ	Ļ	$\downarrow$	↓	$\downarrow$ $\downarrow$
	1	0	1	1	0	1	1	X11-Y6
	0	0	0	0	1	1	1	X0-Y7
	$\downarrow$	$\downarrow \downarrow$						
	1	0	1	1	1	1	1	X11-Y7

Table 1 - Address Decode Truth Table

This address has no effect on device status.

WARNING: X ranges from 0 to 5 and 8 to D, while Y ranges from 0 to 7

0 -> X0 1 -> X1 2 -> X2 3 -> X3 4 -> X4 5 -> X5 8 -> X6 9 -> X7 A -> X8 B -> X9 C -> X10 D -> X11



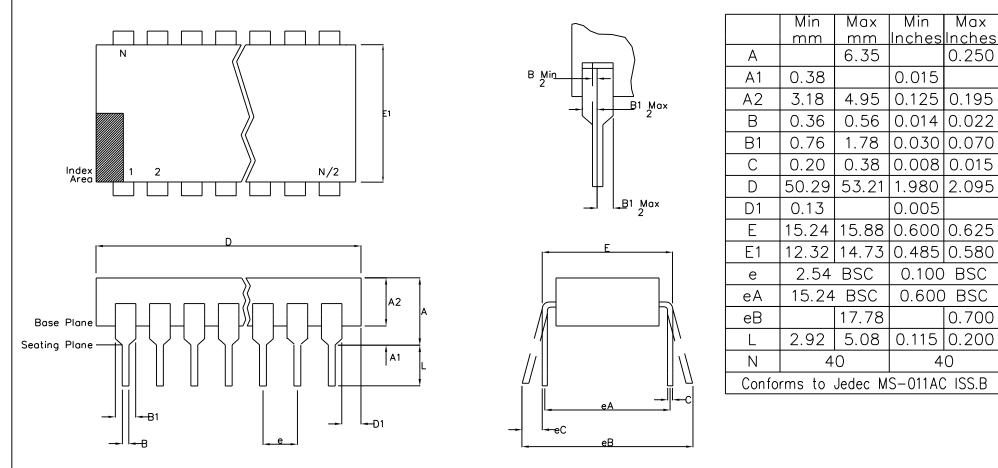
	Control Di	imensions	Altern. Di	mensions				
Symbol	in inc	hes	in millimetres					
	MIN	MAX	MIN	MAX				
А	0.165	0.180	4.19	4.57				
A1	0.090	0.120	2.29	3.05				
A2	0.062	0.083	1.57	2.11				
Α3	0.042	0.056	1.07	1.42				
Α4	0.020		0.51	-				
D	0.685	0.695	17.40	17.65				
D1	0.650	0.656	16.51	16.66				
D2	0.291	0.319	7.39	8.10				
Е	0.685	0.695	17.40	17.65				
E1	0.650	0.656	16.51	16.66				
E2	0.291	0.319	7.39	8.10				
В	0.026	0.032	0.66	0.81				
b	0.013	0.021	0.33	0.53				
е	0.050	BSC	1.27	BSC				
		Pin fea	otures					
ND		11						
NE		11						
Ν		44						
Note		Squo	ore					
Confor	ms to J	EDEC MS		lss. A				

#### Notes:

Seating Plane

- 1. All dimensions and tolerances conform to ANSI Y14.5M-1982
- 2. Dimensions D1 and E1 do not include mould protrusions. Allowable mould protrusion is 0.010" per side. Dimensions D1 and E1 include mould protrusion mismatch and are determined at the parting line, that is D1 and E1 are measured at the extreme material condition at the upper or lower parting line.
- 3. Controlling dimensions in Inches.
- 4. "N" is the number of terminals.
- 5. Not To Scale
- 6. Dimension R required for 120° minimum bend.

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ISSUE	1	2	3			Previous package codes	Package Outline for
ACN	5958	207470	213094		SEMICONDUCTOR		44 lead PLCC
DATE	15Aug94	10Sep99	15Jul02			,	
APPRD.							GPD00003



Notes:

- 1. Controlling Dimensions are in inches
- Controlling Dimensions are in increas
  Dimension A, A1 and L are measured with the package seated in the Seating Plane
  Dimensions D & E1 do not include mould flash or protrusions. Mould flash or protrusion shall not exceed 0.010 inch.
  Dimensions E & eA are measured with leads constrained to be perpendicular to plane T.
- 5. Dimensions eB & eC are measured at the lead tips with the leads unconstrained; eC must be zero or greater.

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ISSUE	1	2	3			Previous package codes	Backage Outline for
ACN	7010	203533	213103		SEMICONDUCTOR		Package Outline for 40 lead PDIP
DATE	20Apr95	25Nov97	15Jul02				
APPRD.							GPD00073



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